

WHAT IS CLAIMED IS:

1. A flexible electrical circuit, including:
one or more electrically conductive traces;
a dielectric layer on a surface of at least one of the traces, the dielectric layer
susceptible to thermal and/or hygroscopic-induced expansion and contraction;
and
slots in the dielectric layer oriented non-parallel to a longitudinal axis of the
conductive traces, to reduce curling caused by thermal and/or hygroscopic-
induced expansion and contraction of the dielectric layer.
2. The flexible electrical circuit of claim 1 wherein the slots are generally parallel
to the longitudinal axis of the conductive traces.
3. The flexible electrical circuit of claim 1 wherein the slots extend only partially
through the dielectric layer.
4. The flexible electrical circuit of claim 1 wherein the slots extend through the
dielectric layer.
5. The flexible electrical circuit of claim 1 wherein the slots have a constant
depth.
6. The flexible electrical circuit of claim 1 wherein the slots have a constant
pitch.
7. The flexible electrical circuit of claim 1 wherein the slots are generally parallel
to one another.

8. The flexible electrical circuit of claim 1 and further including a layer of material on a side of the traces opposite the dielectric layer.
9. The flexible electrical circuit of claim 8 wherein the layer of material on the side of the traces opposite the dielectric layer is a layer of metal.
10. The flexible electrical circuit of claim 8 wherein the layer of material on the side of the traces opposite the dielectric layer is a layer of polymer.
11. An integrated lead flexure, including:
 - a base layer;
 - a plurality of elongated electrical traces on the base layer;
 - a dielectric coverlay over at least portions of the traces; and
 - slots in at least portions of the coverlay oriented non-parallel to a longitudinal axis of the traces.
12. The integrated lead flexure of claim 11 wherein the slots are generally parallel to the longitudinal axis of the conductive traces.
13. The integrated lead flexure of claim 11 wherein the slots extend only partially through the coverlay.
14. The integrated lead flexure of claim 11 wherein the slots extend through the coverlay.
15. The integrated lead flexure of claim 11 wherein the slots have a constant depth.
16. The integrated lead flexure of claim 11 wherein the slots have a constant pitch.

17. The integrated lead flexure of claim 11 wherein the slots are generally parallel to one another.

18. An integrated lead flexure, including:

a stainless steel layer;

a plurality of elongated electrical traces over the stainless steel layer;

a dielectric insulating layer between the stainless steel layer and the electrical traces;

a dielectric coverlay over at least portions of the traces; and

slots in at least portions of the coverlay oriented non-parallel to a longitudinal axis of the traces.

19. The integrated lead flexure of claim 18 wherein the slots are generally parallel to the longitudinal axis of the conductive traces.

20. The integrated lead flexure of claim 18 wherein the slots extend only partially through the coverlay.

21. The integrated lead flexure of claim 18 wherein the slots extend through the coverlay.

22. The integrated lead flexure of claim 18 wherein the slots have a constant depth.

23. The integrated lead flexure of claim 18 wherein the slots have a constant pitch.

24. The integrated lead flexure of claim 18 wherein the slots are generally parallel to one another.

25. The integrated lead flexure of claim 24 wherein the slots are generally parallel to the longitudinal axis of the conductive traces.